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- ☐ 5. Investigation of fundamental EMI source mechanisms driving common-mode radiation from boards with attached cables
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- ☐ 2. Analysis of 3-D Interconnect structures with PEEC using SPICE
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[Very Large Scale Integration \(VLSI\) Systems, IEEE Transactions on](#)
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- ☐ 3. Analysis of power/ground-plane EMI decoupling performance using the partial-element equivalent
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